Electronic Patent Application Fee Transmittal							
Application Number:	10023819						
Filing Date:	21-Dec-2001						
Title of Invention:	CHIP-JOIN PROCESS TO REDUCE ELONGATION MISMATCH BETWEEN THE ADHERENTS AND SEMICONDUCTOR PACKAGE MADE THEREBY						
First Named Inventor:	Biju Chandran						
Filer:	Joseph P. Mehrle/Anne Richards						
Attorney Docket Number:	219.40779X00						
Filed as Large Entity							
Utility Filing Fees							
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Petition fee- 37 CFR 1.17(h) (Group III)		1464	1	130	130		
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Extension-of-Time:							

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	790	790
	Tota	920		